

P S T

D C R 1 1 8 0 F - Power Thyristor

5200V<sub>DRM</sub>; 1180 A rms

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**HIGH POWER THYRISTOR FOR PHASE CONTROL APPLICATIONS****Features:**

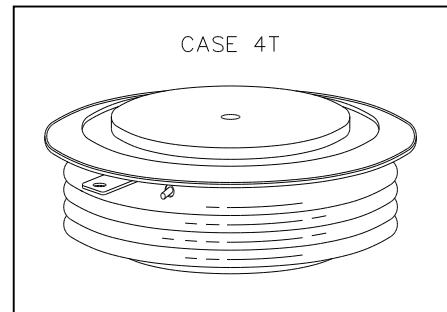
- . All Diffused Structure
- . Center Amplifying Gate Configuration
- . Blocking capability up to 5200 volts
- . Guaranteed Maximum Turn-Off Time
- . High dV/dt Capability
- . Pressure Assembled Device

**ELECTRICAL CHARACTERISTICS AND RATINGS****Blocking - Off State**

Device Type	V <sub>RRM</sub> (1)	V <sub>DRM</sub> (1)	V <sub>RSM</sub> (1)
DCR1180F4800	4800	4800	4900
DCR1180F5000	5000	5000	5100
DCR1180F5200	5200	5200	5300

V<sub>RRM</sub> = Repetitive peak reverse voltageV<sub>DRM</sub> = Repetitive peak off state voltageV<sub>RSM</sub> = Non repetitive peak reverse voltage (2)

Repetitive peak reverse leakage and off state leakage	I <sub>RRM</sub> / I <sub>DRM</sub>	50 mA
Critical rate of voltage rise	dV/dt (4)	1500 V/μsec

**Conducting - on state**

## Notes:

All ratings are specified for T<sub>j</sub>=25 °C unless otherwise stated.

(1) All voltage ratings are specified for an applied 50Hz/60Hz sinusoidal waveform over the temperature range -40 to +125 °C.

(2) 10 msec. max. pulse width

(3) Maximum value for T<sub>j</sub> = 125 °C.

(4) Minimum value for linear and exponential waveshape to 80% rated V<sub>DRM</sub>. Gate open. T<sub>j</sub> = 125 °C.

(5) Non-repetitive value.

(6) The value of di/dt is established in accordance with EIA/NIMA Standard RS-397, Secti5-2-2-6. The value defined would be in addition to that obtained from a snubber circuit comprising a 0.2 μF capacitor and 20 ohms resistance in parallel with the thristor under test.

Parameter	Symbol	Min.	Max.	Ty p.	Units	Conditions
Average value of on-state current	I <sub>T(AV)</sub>		1180		A	Sinewave, 180° conduction, T <sub>c</sub> =65°C
RMS value of on-state current	I <sub>TRMS</sub>		1854		A	Nominal value
Peak one cycle surge (non repetitive) current	I <sub>TSM</sub>		15900		A	10.0 msec (50Hz), sinusoidal wave-shape, 180° conduction, T <sub>j</sub> = 125 °C
I square t	I <sup>2</sup> t		1.26x10 <sup>6</sup>		A <sup>2</sup> s	10.0 msec
Latching current	I <sub>L</sub>		800		mA	V <sub>D</sub> = 24 V; R <sub>L</sub> = 12 ohms
Holding current	I <sub>H</sub>		400		mA	V <sub>D</sub> = 24 V; I = 2.5 A
Peak on-state voltage	V <sub>TM</sub>		2.5		V	I <sub>TM</sub> = 3000A; Duty cycle ≤ 0.01%
Threshold voltage	V <sub>TO</sub>		1.2		V	T <sub>j</sub> = 125 °C
Slope resistance	r <sub>T</sub>		0.57		m Ω	T <sub>j</sub> = 125 °C
Critical rate of rise of on-state current (5, 6)	di/dt		300		A/μs	Switching from V <sub>DRM</sub> ≤ 1000 V, non-rep
Critical rate of rise of on-state current (6)	di/dt		150		A/μs	Switching from V <sub>DRM</sub> ≤ 1000 V

**ELECTRICAL CHARACTERISTICS AND RATINGS (cont'd)****DCR1180F- Power Thyristor****Gating**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Peak gate power dissipation	P <sub>GM</sub>		200		W	t <sub>p</sub> = 40 us
Average gate power dissipation	P <sub>G(AV)</sub>		5		W	
Peak gate current	I <sub>GM</sub>		10		A	
Gate current required to trigger all units	I <sub>GT</sub>		300		mA	V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = +25 °C
Gate voltage required to trigger all units	V <sub>GT</sub>		3		V	V <sub>D</sub> = 6 V; R <sub>L</sub> = 3 ohms; T <sub>j</sub> = 25°C
Peak negative voltage	V <sub>GRM</sub>		5		V	

**Dynamic**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Delay time	t <sub>d</sub>		1.5	0.7	μs	I <sub>TM</sub> = 50 A; V <sub>D</sub> = Rated V <sub>DRM</sub> Gate pulse: V <sub>G</sub> = 20 V; R <sub>G</sub> = 20 ohms; t <sub>r</sub> = 0.1 μs; t <sub>p</sub> = 20 μs
Turn-off time (with V <sub>R</sub> = -50 V)	t <sub>q</sub>		250	150	μs	I <sub>TM</sub> = 1000 A; di/dt = 25 A/μs; V <sub>R</sub> ≥ -50 V; Re-applied dV/dt = 20 V/μs linear to 80% V <sub>DRM</sub> ; V <sub>G</sub> = 0; T <sub>j</sub> = 125 °C; Duty cycle ≥ 0.01%
Reverse recovery charge	Q <sub>rr</sub>		*		μC	I <sub>TM</sub> = 1000 A; di/dt = 25 A/μs; V <sub>R</sub> ≥ -50 V

\* For guaranteed max. value, contact factory.

**THERMAL AND MECHANICAL CHARACTERISTICS AND RATINGS**

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Operating temperature	T <sub>j</sub>	-40	+125		°C	
Storage temperature	T <sub>stg</sub>	-40	+150		°C	
Thermal resistance - junction to case	R <sub>θ(j-c)</sub>		0.025		°C/W	Double sided cooled
Thermal resistamce - case to sink	R <sub>θ(c-s)</sub>		0.010		°C/W	Double sided cooled *
Mounting force	P	5500 24.5	6000 26.7		lb. kN	
Weight	W			16 460	oz. g	

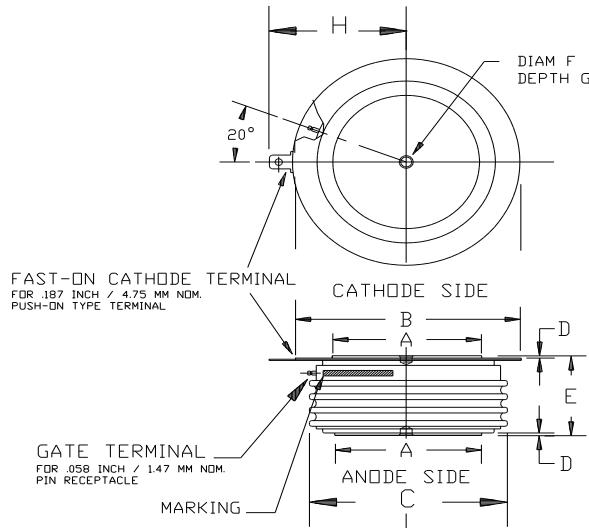
\* Mounting surfaces smooth, flat and greased

# Technical Data : CD-031

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## CASE OUTLINE AND DIMENSIONS.

## DCR1180F- Power Thyristor



STRIKE DISTANCE = .58 INCH / 14.7 MM MIN.  
CREEPAGE DISTANCE = 1.00 INCH / 25.4 MM MIN.

OUTLINE DIMENSIONS - CASE 4T				
DIMENSIONS	Min. mm	Max. mm	Min. In.	Max. In.
DIAM A	43.18	48.26	1.70	1.90
DIAM B	63.50	75.18	2.50	2.96
DIAM C	--	67.31	--	2.65
D	0.76	--	0.03	--
E	25.40	27.18	1.00	1.07
F	3.30	3.81	0.13	0.15
G	1.78	2.03	0.07	0.08
H	--	44.20	--	1.74